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(54) **INTERPOSER BOARD AND CIRCUIT BOARD INCLUDING THE SAME**

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(71) Applicant: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**, Suwon-si (KR)

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(72) Inventors: **Young Kuk Ko**, Suwon-si (KR); **Sanghoon Kim**, Suwon-si (KR); **Jiho Yoon**, Suwon-si (KR); **Gyumook Kim**, Suwon-si (KR); **Taehun Kim**, Suwon-si (KR); **Sukchang Hong**, Suwon-si (KR); **Seongil Jeon**, Suwon-si (KR); **Woo-Jeong Choi**, Suwon-si (KR)

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(73) Assignee: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**, Suwon-si (KR)

(57) **ABSTRACT**

A circuit board according to an embodiment includes: a first substrate; and an interposer board that is located on the first substrate, and includes a first insulating layer having a first surface and a second surface facing each other, a first wiring layer buried in the first surface of the first insulating layer, a second insulating layer located on the second surface of the first insulating layer, a cavity disposed in a part of the first insulating layer, and a first trench connected to the cavity; an electronic component disposed between the first substrate and the interposer board, and at least partially disposed in the cavity; and a molding layer located between the first substrate and the interposer board.

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